

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Application Number	10/589599
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First Named Inventor	Fuller, Edward Nelson
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Examiner Name	Rost, Andrew J.
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Examiner Initials*	Cite No.	Patent Number	Kind Code1	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1	US-7372074		5/13/2008	Milne et al.	

NON-PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.		T5
	1	Gui, C. et al., "Selective Wafer Bonding by Surface Roughness Control", Journal of The Electrochemical Society, 148 (4) G225-G228 (2001)	
	2	Gui, C. et al., "Fusion bonding of rough surfaces with polishing technique for silicon micromachining", Microsystem Technologies (1997) 122-128	
	3	Zhixiong Liu et al., "Micromechanism fabrication using silicon fusion bonding", Robotics and Computer Integrated Manufacturing 17 (2001) 131-137	

Examiner Signature	Date Considered
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